

ABSTRACT OF THE DISCLOSURE

An object of the present invention is to provide a coil chip having a structure with which downsizing of the coil chip can be realized and a high inductance and a high Q can be obtained and to provide a method of producing such a coil chip. In order to attain the object, according to the present invention, there is provided a coil structure including a core member made of a material having low dielectric loss characteristics, a coil formed by metal plating and wound around the core member, and a layer functioning as a seed for metal plating provided between the core member and the coil.